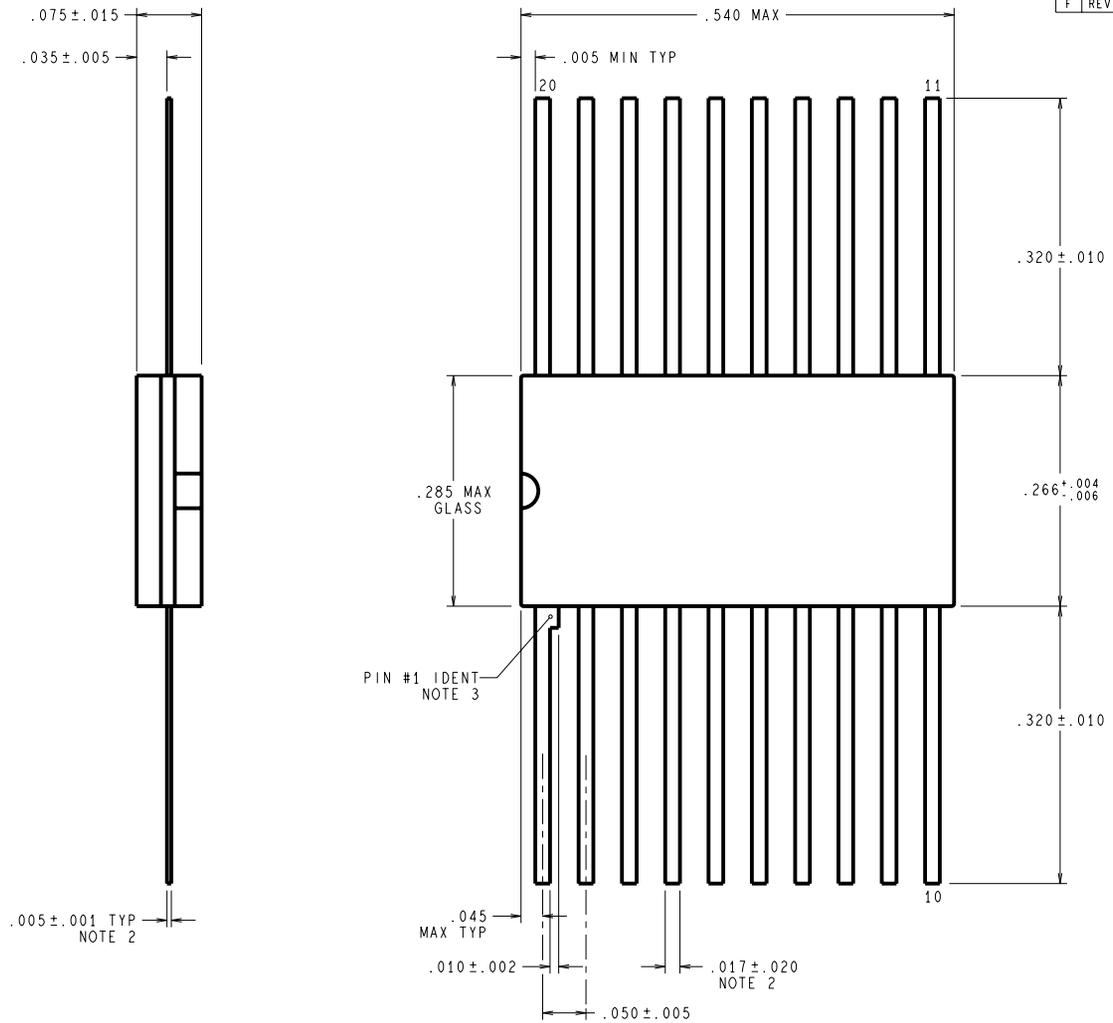


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	REVISE AND REDRAW PER NEW STANDARD.	10512	07/28/94	DEG/



NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-M-38510 TO A MINIMUM THICKNESS OF 200 MICROINCHES. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
2. MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES AFTER LEAD FINISH APPLIED.
3. LEAD 1 IDENTIFICATION SHALL BE:
  - a) A NOTCH OR OTHER MARK WITHIN THIS AREA
  - b) A TAB ON LEAD 1, EITHER SIDE
4. NO JEDEC REGISTRATION AS OF 02/70/94.

MIL/AERO  
CONFIGURATION CONTROL

MIL-M-38510  
CONFIGURATION CONTROL

<b>APPROVALS</b>		<b>DATE</b>		 <b>National Semiconductor</b> 2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DRAWN		07/28/94					
DFTG. CHK.							
ENGR. CHK.							
<b>CERPACK, 20 LEAD</b>				SCALE	SIZE	DRAWING NUMBER	REV
 PROJECTION <small>INCH (MM)</small>				N/A	C	MKT-W20A	F
DO NOT SCALE DRAWING				SHEET 1 of 1			